TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSIII)

# SSM6P26TU

#### High Speed Switching Applications

- Optimum for high-density mounting in small packages
- Low on-resistance:  $R_{on} = 230m\Omega (max) (@V_{GS} = -4 V)$ 
  - $R_{on} = 330m\Omega \text{ (max)} (@V_{GS} = -2.5 \text{ V})$

 $R_{on} = 980 m\Omega \text{ (max)} (@V_{GS} = -1.8 \text{ V})$ 

#### Absolute Maximum Ratings (Ta = 25°C) (Q1, Q2 Common)

| Characteristics           |       | Symbol                     | Rating  | Unit |  |
|---------------------------|-------|----------------------------|---------|------|--|
| Drain-Source voltage      |       | V <sub>DS</sub>            | -20     | V    |  |
| Gate-Source voltage       |       | V <sub>GSS</sub>           | ± 8     | V    |  |
| Drain current             | DC    | Ι <sub>D</sub>             | -0.5    | A    |  |
|                           | Pulse | I <sub>DP</sub>            | -1.5    |      |  |
| Drain power dissipation   |       | P <sub>D</sub><br>(Note 1) | 500     | mW   |  |
| Channel temperature       |       | T <sub>ch</sub>            | 150     | °C   |  |
| Storage temperature range |       | T <sub>stg</sub>           | -55~150 | °C   |  |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

2.1±0.1 1.7±0.1 65 6 2.0±0.1 3±0. 5 3 750 1.Source1 4.Source2 2.Gate1 5.Gate2 3.Drain2 6.Drain1 JF6 JEDEC \_ JEITA TOSHIBA 2-2T1B

Weight: 7.0 mg (typ.)

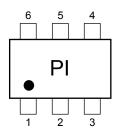
Please design the appropriate reliability upon reviewing the

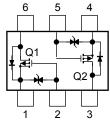
Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on FR4 board. (total dissipation) (25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu Pad: 645 mm  $^2$  )

Marking

# Equivalent Circuit (top view)





# **Handling Precaution**

When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

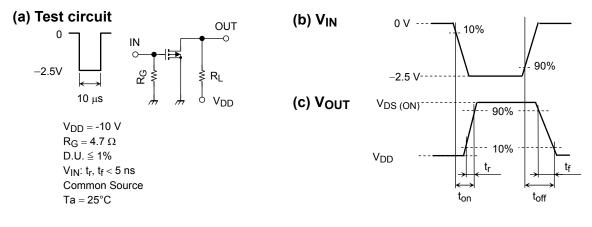


## Electrical Characteristics (Ta = 25°C) (Q1, Q2 Common)

| Chara                          | cteristics    | Symbol  | Test Condition  |         | Min  | Тур. | Max  | Unit |
|--------------------------------|---------------|---|---|---------|------|------|------|------|
| Gate leakage curr              | ent           | I <sub>GSS</sub>                                      | $V_{GS} = \pm 8 V, V_{DS} = 0$  |         | _    |      | ±1   | μA   |
| Drain-Source breakdown voltage |               | V (BR) DSS  | $I_D = -1 \text{ mA}, V_{GS} = 0$ $I_D = -1 \text{ mA}, V_{GS} = +8 \text{ V}$                    |         | -20  |      |      | V    |
|                                |               | V (BR) DSX  |   |         | -12  | _    | _    |      |
| Drain cut-off curre            | nt            | I <sub>DSS</sub>                                      | $V_{DS} = -20 V, V_{GS} = 0$  |         | _    | _    | -1   | μA   |
| Gate threshold vo              | Itage         | V <sub>th</sub>                                       | $V_{DS} = -3 V, I_D = -0.1 mA$  |         | -0.5 | _    | -1.1 | V    |
| Forward transfer a             | admittance    | Y <sub>fs</sub>                                       | $V_{DS} = -3 V, I_D = -0.25 A$  | (Note2) | 0.8  | 1.7  | _    | S    |
| Drain-Source on-resistance     |               | R <sub>DS (ON)</sub>                                  | $I_D = -0.25 \text{ A}, \text{ V}_{GS} = -4 \text{ V}$  | (Note2) | _    | 200  | 230  | mΩ   |
|                                |               |   | $I_D = -0.25 \text{ A}, \text{ V}_{GS} = -2.5 \text{ V}$  | (Note2) | _    | 260  | 330  |      |
|                                |               |   | I <sub>D</sub> = -0.25 A, V <sub>GS</sub> = -1.8 V  | (Note2) | _    | 400  | 980  |      |
| Input capacitance              |               | $C_{iss}$ $V_{DS} = -10 V$ , $V_{GS} = 0$ , f = 1 MHz |   | IHz     | _    | 250  | _    | pF   |
| Reverse transfer capacitance   |               | C <sub>rss</sub>                                      | $V_{DS} = -10 \text{ V},  V_{GS} = 0,  f = 1  \text{MHz}$   |         | _    | 35   | _    | pF   |
| Output capacitance             |               | C <sub>oss</sub>                                      | $V_{DS} = \textbf{-10 V},  V_{GS} = \textbf{0},  \textbf{f} = \textbf{1}   \textbf{MHz}$          |         | _    | 45   |      | pF   |
| Switching time                 | Turn-on time  | t <sub>on</sub>                                       | $V_{DD}$ = -10 V, I <sub>D</sub> = -0.25 A,<br>V <sub>GS</sub> = 0~-2.5 V, R <sub>G</sub> = 4.7 Ω |         | _    | 14   |      | ns   |
|                                | Turn-off time | t <sub>off</sub>                                      |   |         | _    | 15   | —    |      |

Note2: Pulse test

# **Switching Time Test Circuit**



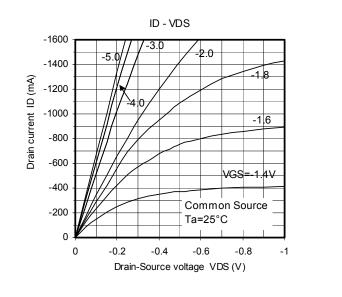
## Precaution

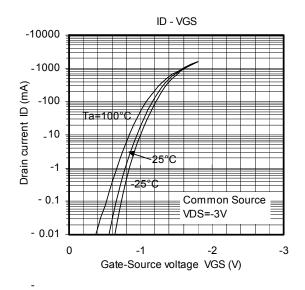
 $V_{th}$  can be expressed as the voltage between gate and source when the low operating current value is I<sub>D</sub>=-100  $\mu A$  for this product. For normal switching operation, V<sub>GS (on)</sub> requires a higher voltage than V<sub>th</sub> and V<sub>GS (off)</sub> requires a lower voltage than V<sub>th</sub>.

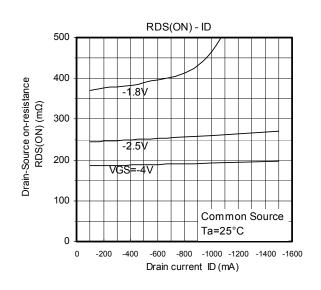
(The relationship can be established as follows:  $V_{GS (off)} < V_{th} < V_{GS (on)}$ )

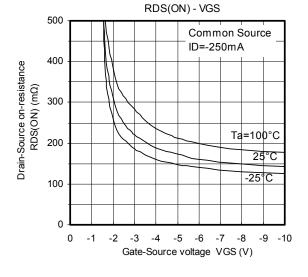
Please take this into consideration when using the device.

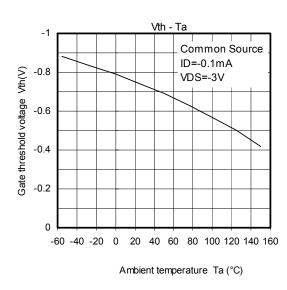
# TOSHIBA





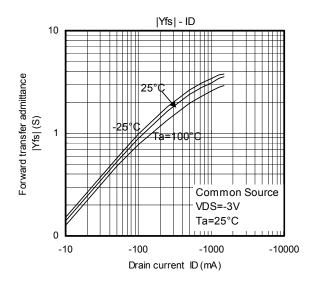


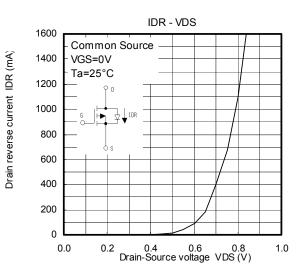


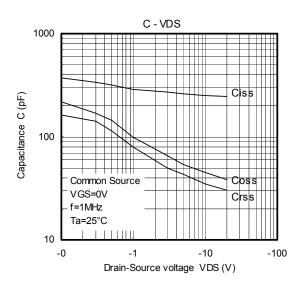


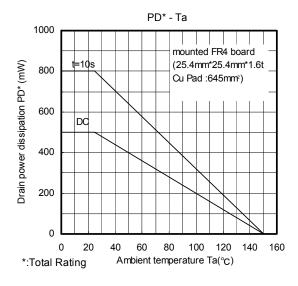
RDS(ON) - Ta 500 -1.8V Common Source ID=-250mA 400 Drain-Source on-resistance 2.5V RDS(ON) (mΩ) 300 VGS=-4 200 100 0 -60 -40 -20 0 20 40 60 80 100 120 140 160 Ambient temperature Ta (°C)

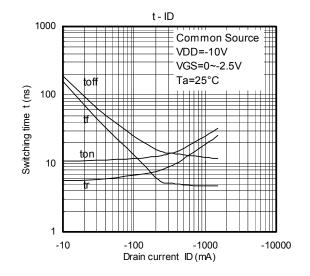
# TOSHIBA

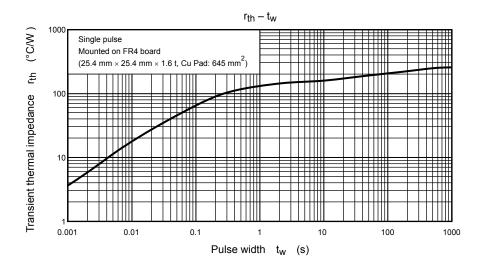












## **RESTRICTIONS ON PRODUCT USE**

20070701-EN GENERAL

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